## Tender of 1-year RMB HKSAR Institutional Government Bonds to be held on March 6

The following is issued on behalf of the Hong Kong Monetary Authority:

The Hong Kong Monetary Authority (HKMA), as representative of the Hong Kong Special Administrative Region Government (HKSAR Government), announced today (March 3) that a tender of 1-year RMB Institutional Government Bonds (Bonds) under the Infrastructure Bond Programme will be held on March 6, 2025 (Thursday), for settlement on March 10, 2025 (Monday).

A total of RMB2.0 billion 1-year RMB Bonds will be tendered. The Bonds will mature on 10 March, 2026 and will carry interest at the rate of 2.12 per cent per annum payable semi-annually in arrear.

Tender is open only to Primary Dealers appointed under the Infrastructure Bond Programme. Anyone wishing to apply for the Bonds on offer can do so through any of the Primary Dealers on the latest published list, which can be obtained from the Hong Kong Government Bonds website at <a href="https://www.hkgb.gov.hk">www.hkgb.gov.hk</a>. Each tender must be for an amount of RMB50,000 or integral multiples thereof.

Tender results will be published on the HKMA's website, the Hong Kong Government Bonds website, Bloomberg (GBHK <GO>) and Refinitiv (IBPGSBPINDEX). The publication time is expected to be no later than 3pm on the tender day.

HKSAR Institutional Government Bonds Tender Information

Tender information of 1-year RMB HKSAR Institutional Government Bonds:

Issue Number : 01GB2603001

Stock Code : 85007 (HKGB2.12 2603-R)
Tender Date and . March 6, 2025 (Thursday)

Time ' 9.30am to 10.30am

Issue and

Settlement Date : March 10, 2025 (Monday)

Amount on Offer : RMB2.0 billion

Maturity : 1 year

Maturity Date : March 10, 2026 (Tuesday)

Interest Rate : 2.12 per cent p.a. payable semi-annually in

arrear

March 10 and September 10 in each year, commencing on the Issue Date up to and including the Maturity Date, subject to adjustment in accordance with the terms of the Institutional Issuances Information

Interest Payment

Dates

the Institutional Issuances Information
Memorandum of the Infrastructure Bond
Programme and Government Sustainable Bond
Programme (Information Memorandum) published
on the Hong Kong Government Bonds website.

Method of Tender : Competitive tender

Each competitive tender must be for an amount of RMB50,000 or integral multiples

Tender Amount : thereof. Any tender applications for the

Bonds must be submitted through a Primary

Dealer on the latest published list.
Please see the Information Memorandum

Other Details : available on the Hong Kong Government Bonds

website or approach Primary Dealers.

Expected

commencement date

of dealing on

the Stock : March 11, 2025 (Tuesday)

Exchange
of Hong Kong
Limited

The Bonds will be issued under the

institutional part of the Infrastructure Bond Programme. Proceeds will be invested in

Use of Proceeds

infrastructure projects in accordance with the Infrastructure Bond Framework published on the Hong Kong Government Bonds website.